EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	220	(encapsulat$6 mold $6 packag$6 resin plastic epoxy) and (semiconductor silicon die dice chip wafer fragment integrated ic component) and (carrier substrate board pwb pcb base) and (cavity space open$6) and (feed$6 assembl$6) and (edge project$6) and (mov$6 displac$6 adjust$6) and (support receiv$6 force part)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/09 08:59
S1	11	ep-726598-$.did. jp-07205214-$.did. jp-07183317-$.did. jp-07080895-$.did. jp-04184944-$.did. jp-57128930-$.did. wo-2001017012-$.did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2008/04/04 11:34
S2	1	wo-0117012-$.did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2008/04/04 11:44
S3	16316	257/787.ccls. 257/e21.502.ccls. 257/e21.504.ccls. 257/e21.705.ccls. 257/e23.116.ccls. 257/e23.125.ccls. 438/108.ccls. 438/124.ccls. 438/126.ccls. 438/127.ccls. 156/500.ccls. 425/117.ccls. 425/125.ccls. 425/128.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2008/04/08 15:05
S4	348	425/128.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2008/04/08 15:07

S5	13000	S3 and ((encapsulat$6 mold$6 packag$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment carrier substrate board pwb pcb integrated ic))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/04/08 15:55
S6	8176	S3 and ((encapsulat$6 mold$6 packag$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment carrier substrate board pwb pcb integrated ic) same (cavity feed$6 assembl$6 edge project$6))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/04/08 16:00
S7	1608	S3 and ((encapsulat$6 mold$6 packag$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment carrier substrate board pwb pcb integrated ic) same (cavity feed$6 assembl$6) same (edge project$6))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/04/08 16:06
S8	876	S3 and ((encapsulat$6 mold$6 packag$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment integrated ic component) same (carrier substrate board pwb pcb base) same (cavity feed$6 assembl$6) same (edge project$6))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/04/08 16:08

S9	351	S3 and ((encapsulat$6 mold$6 packag$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment integrated ic component) same (carrier substrate board pwb pcb base) same (cavity feed$6 assembl$6) same (edge project$6) same (movable displac$6 support receiv$6 force part))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/04/08 16:13
S10	2809	(encapsulat$6 mold$6 packag$6 resin plastic epoxy) and (semiconductor silicon die dice chip wafer fragment integrated ic component) and (carrier substrate board pwb pcb base) and (cavity feed$6 assembl$6) and (edge project$6) and (movable displac$6 support receiv$6 force part)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 16:14
S11	838	(encapsulat$6 mold$6 packag$6 resin plastic epoxy) and (semiconductor silicon die dice chip wafer fragment integrated ic component) and (carrier substrate board pwb pcb base) and (cavity space open$6) and (feed$6 assembl$6) and (edge project$6) and (movable displac$6 support receiv$6 force part)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 16:16

S12	68	(encapsulat$6 mold $6 packag$6 resin plastic epoxy) and (semiconductor silicon die dice chip wafer fragment integrated ic component) and (carrier substrate board pwb pcb base) and (cavity space open$6) and (feed$6 assembl$6) and (edge project$6) and (movable displac$6) and (support receiv$6 force part)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 16:17
S13	103	(encapsulat$6 mold $6 packag$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment integrated ic component) same (carrier substrate board pwb pcb base) same (cavity space open$6) same (feed $6 assembl$6) same (edge project$6) same (movable displac $6) same (support receiv$6 force part)	US-PGPUB; USPAT	OR	ON	2008/04/08 16:19
S16	364	(encapsulat$6 mold $6 packag$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment integrated ic component) same (carrier substrate board pwb pcb base) same (cavity space open$6) same (feed $6 assembl$6) same (edge project$6) same (mov$6 displac $6 adjust$6) same (support receiv$6 force part)	US-PGPUB; USPAT	OR	ON	2008/04/08 23:20

4/9/08 10:10:59 AM
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